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CLAIMS

1. A copper-based alloy containing at least 2.8 to 5.0 wt% of Sn, 0.4 to 3.0 wt% of Bi and satisfying $0 < \text{Se} \leq 0.35$ wt% to enable securing prescribed machinability and wholesome
5 ness of a casting and exalt mechanical properties thereof.
2. A copper-based alloy according to claim 1, wherein it contains the Se of 0.2 wt% or less.
3. A copper-based alloy according to claim 1 or claim 2, wherein it contains the Sn in a range of 3.5 to 4.5 wt%.
4. A copper-based alloy according to any one of claims 1 to 3, wherein it further satisfies 0
10 $< \text{P} < 0.5$ wt%.
5. A copper-based alloy according to any one of claims 1 to 4, wherein it further contains Ni of 3.0 wt% or less.
6. A copper-based alloy containing at least Sn, Bi and Se and containing at least one non-solid solution substance formed of an alternative component for Pb in an amount of 1.0
15 vol% or more to enable suppression of occurrence of a casting defect.
7. A copper-based alloy according to claim 6, wherein it contains the at least one non-solid solution substance secured with Bi.
8. A copper-based alloy according to claim 6, wherein it contains the at least one non-solid solution substance secured with Bi and Se.
- 20 9. A copper-based alloy according to any one of claims 6 to 8, wherein it contains the at least one non-solid solution substance of 4.90 vol% or less.
10. A cast ingot produced using the alloy according to any one of claims 1 to 9 and a liquid-contacting part formed of the cast ingot.